

**NONPROVISIONAL PATENT
APPLICATION TRANSMITTAL RULE §1.53(b)
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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Docket No. 108384-00034
Date: November 30, 2001

Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a nonprovisional patent application:

For (Title): RESIN COMPOUND FOR FABRICATING INTERLAYER DIELECTRIC OF
PRINTED WIRING BOARD, RESIN SHEET AND RESIN APPLIED-
COPPER FOIL FOR FORMING INSULATING LAYER USING THE RESIN
COMPOUND, AND COPPER-CLAD LAMINATE USING THEM

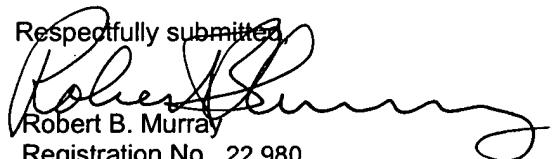
By (Inventors): Tetsuro SATO and Tsutomu ASAI

- 33 pages of Specification/Claims 1-12/Abstract are attached.
- A Declaration and Power of Attorney is attached.
- An assignment of the invention to Mitsui Mining & Smelting Co., Ltd. is attached, along with Form PTO-1595 and a check for \$40.00.
- A Preliminary Amendment is attached.
- Priority of foreign application No. 2000-374070 filed December 8, 2000 in Japan is claimed under 35 U.S.C. §119.
- A certified copy of the above corresponding foreign application is attached.

The filing fee is calculated below and includes claim status after entry of any Preliminary Amendment noted above:

			SMALL ENTITY		LARGE ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEES	RATE	FEES
BASIC FEE				\$ 370		\$ 740
TOTAL CLAIMS	12 - 20	= 0	x 9 =	\$	x 18	\$
INDEP CLAIMS	1 - 3	= 0	x 42 =	\$	x 84	\$
<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS			+140 =	\$	+280	\$
			TOTAL	\$	TOTAL	\$ 740

- A check in the amount of \$780.00 (\$740.00 for the filing fee and \$40.00 for the Assignment Recordation Fee) is attached. Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300.

Respectfully submitted,

 Robert B. Murray
 Registration No. 22,980

RBM//ars